

Digital FET, N-Channel FDV301N, FDV301N-F169

General Description

This N-Channel logic level enhancement mode field effect transistor is produced using **onsemi's** proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for digital transistors. Since bias resistors are not required, this one N-channel FET can replace several different digital transistors, with different bias resistor values.

Features

- 25 V, 0.22 A Continuous, 0.5 A Peak
 - $R_{DS(on)} = 5 \Omega @ V_{GS} = 2.7 V$
 - $R_{DS(on)} = 4 \Omega @ V_{GS} = 4.5 V$
- Very Low Level Gate Drive Requirements Allowing Direct Operation in 3 V Circuits. V_{GS(th)} < 1.06 V
- Gate-Source Zener for ESD Ruggedness. > 6 kV Human Body Model
- Replace Multiple NPN Digital Transistors with One DMOS FET
- This Device is Pb-Free and Halide Free

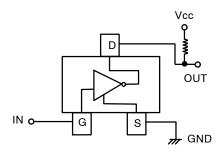
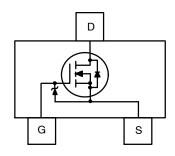


Figure 1. Inverter Application





SOT-23 CASE 318-08

MARKING DIAGRAM



&E = Designates Space &Y = Binary Calendar Year Coding Scheme

301 = Specific Device Code

&G = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
FDV301N, FDV301N-F169	SOT-23-3 (Pb-Free, Halide-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ABSOLUTE MAXIMUM RATINGS T_A = $25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	FDV301N	Unit
V _{DSS} , V _{CC}	Drain-Source Voltage, Power Supply Voltage	25	V
V _{GSS} , V _I	Gate-Source Voltage, V _{IN}	8	V
I _D , I _O	Drain/Output Current - Continuous	0.22	Α
		0.5	
P _D	Maximum Power Dissipation	0.35	W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 150	°C
ESD	Electrostatic Discharge Rating MIL–STD–883D Human Body Model (100 pF/1500 Ω)	6.0	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS T_A = 25°C unless otherwise noted.

Symbol	Parameter	Value	Unit
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W

INVERTER ELECTRICAL CHARACTERISTICS $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
I _{O(off)}	Zero Input Voltage Output Current	V _{CC} = 20 V, V _I = 0 V	-	-	1	μΑ
V _{I(off)}	Input Voltage	$V_{CC} = 5 \text{ V}, I_{O} = 10 \mu\text{A}$	-	_	0.5	V
V _{I(on)}		$V_O = 0.3 \text{ V}, I_O = 0.005 \text{ A}$	1	_	_	
R _{O(on)}	Output to Ground Resistance	V _I = 2.7 V, I _O = 0.2 A	-	4	5	Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ELECTRICAL CHARACTERISTICS $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit			
OFF CHARACT	DFF CHARACTERISTICS								
BV _{DSS}	Drain-Source Breakdown Voltage	25	-	_	V				
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25°C	-	25	-	mV/°C			
I _{DSS}	Zero Gate Voltage Drain Current V _{DS} = 20 V, V _{GS} = 0 V		-	-	1	μΑ			
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55°C	-	-	10				
I _{GSS}	Gate - Body Leakage Current	V _{GS} = 8 V, V _{DS} = 0 V	-	-	100	nA			
ON CHARACTERISTICS									
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25°C	_	-2.1	-	mV/°C			
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.70	0.85	1.06	V			
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 2.7 V, I _D = 0.2 A	-	3.8	5	Ω			
		$V_{GS} = 2.7 \text{ V}, I_D = 0.2 \text{ A}, T_J = 125^{\circ}\text{C}$	-	6.3	9				
		V _{GS} = 4.5 V, I _D = 0.4 A	-	3.1	4				
I _{D(on)}	On-State Drain Current	V _{GS} = 2.7 V, V _{DS} = 5 V	0.2	-	-	Α			
9FS	Forward Transconductance	V _{DS} = 5 V, I _D = 0.4 A	-	0.2	_	S			

ELECTRICAL CHARACTERISTICS T_A = 25°C unless otherwise noted. (continued)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
YNAMIC CH	ARACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 10 V, V _{GS} = 0 V, f = 1.0 MHz	-	9.5	_	pF
C _{oss}	Output Capacitance		-	6	_	
C _{rss}	Reverse Transfer Capacitance		-	1.3	-	
WITCHING (CHARACTERISTICS (Note 1)					
t _{D(on)}	Turn - On Delay Time	$V_{DD} = 6 \text{ V}, I_{D} = 0.5 \text{ A}, V_{GS} = 4.5 \text{ V},$	-	3.2	8	ns
t _r	Turn – On Rise Time	$R_{GEN} = 50 \Omega$		6	15	
t _{D(off)}	Turn – Off Delay Time		-	3.5	8	
t _f	Turn – Off Fall Time		-	3.5	8	
Qg	Total Gate Charge	$V_{DS} = 5 \text{ V}, I_D = 0.2 \text{ A}, V_{GS} = 4.5 \text{ V}$	-	0.49	0.7	nC
Q _{gs}	Gate-Source Charge		-	0.22	_	
Q_{gd}	Gate-Drain Charge		-	0.07		
RAIN-SOUF	RCE DIODE CHARACTERISTICS AND M	AXIMUM RATINGS				
Is	Maximum Continuous Drain-Source Di	Maximum Continuous Drain-Source Diode Forward Current			0.29	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0.29 A (Note 1)	-	0.8	1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

TYPICAL CHARACTERISTICS

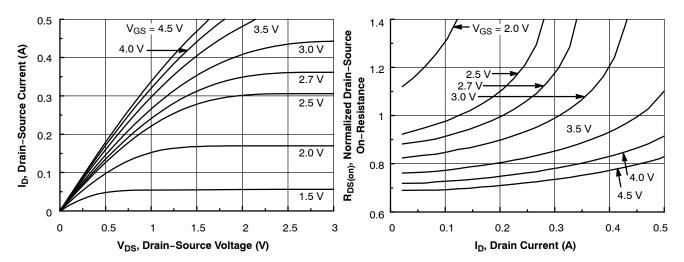
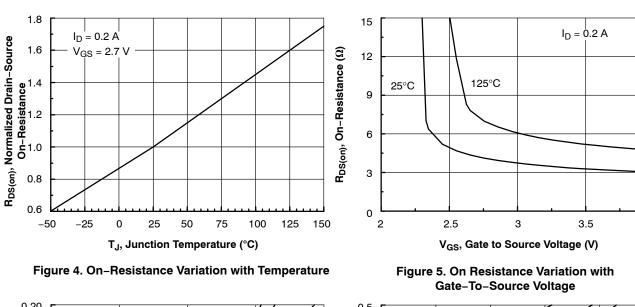


Figure 2. On-Region Characteristics

Figure 3. On-Resistance Variation with Drain Current and Gate Voltage

TYPICAL PERFORMANCE CHARACTERISTICS (continued)



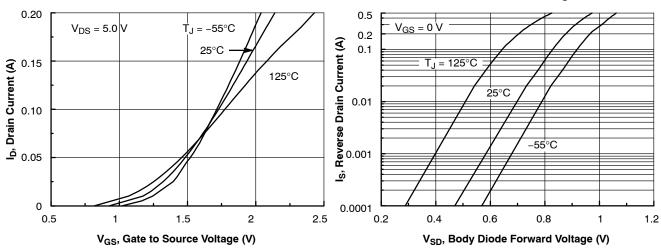


Figure 6. Transfer Characteristics

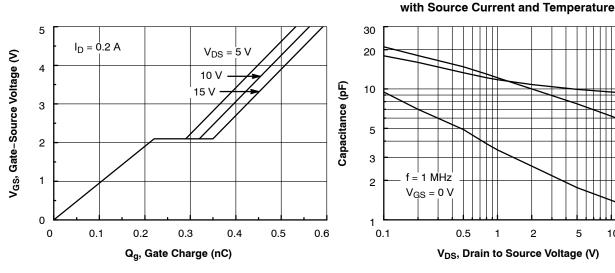


Figure 8. Gate Charge Characteristics

Figure 9. Capacitance Characteristics

Figure 7. Body Diode Forward Voltage Variation

 $C_{\underline{iss}}$

Coss

 C_{rss}

25

10

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

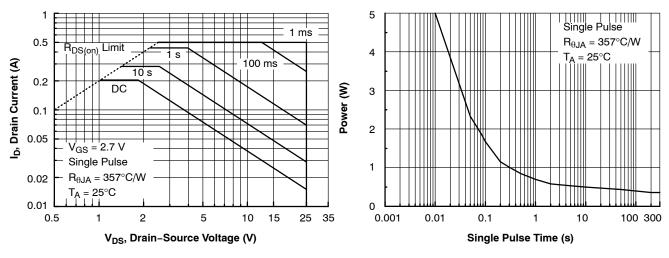


Figure 10. Maximum Safe Operating Area

Figure 11. Single Pulse Maximum Power Dissipation

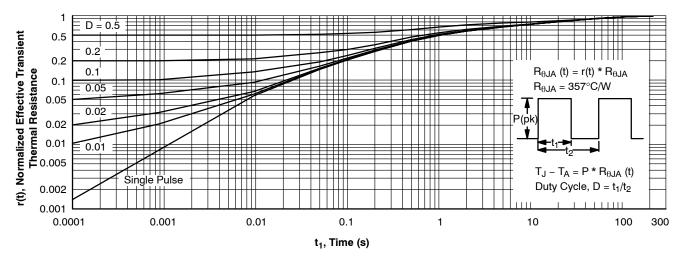


Figure 12. Transient Thermal Response Curve

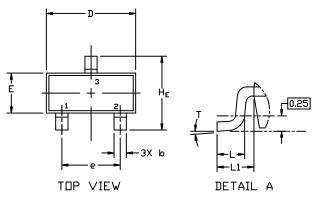


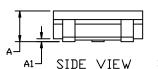


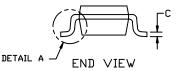
SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023









NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	IETERS		INCHES		
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

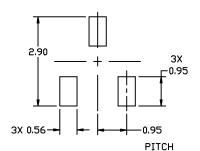
GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42226B	Electronic versions are uncontrolled except when accessed directly from the Document Repo Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOT-23 (TO-236)		PAGE 1 OF 2	

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE		PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE		2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE		3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	N PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

DOCUMENT NUMBER:	98ASB42226B	Electronic versions are uncontrolled except when accessed directly from the Document Reposit Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOT-23 (TO-236)		PAGE 2 OF 2	

onsemi and ONSEMi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative